



3rd Workshop on LHCb Upgrade II

LAPP, 22 – 23 March 2017



A High Granularity Timing Detector for the Phase II Upgrade of the ATLAS experiment

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ON BEHALF OF THE ATLAS HGTD COMMUNITY



Institut de Física d'Altes Energies

Annecy – March 22nd, 2018

•Overview

Introduction

- ATLAS and HL-HLC

HGTD System

- Geometry and design

Sensors

- Low Gain Avalanche Diodes

Integration

- Electronics and services

Physics

- Physics and Performance

Luminometer

- Online and off-line luminosity estimation

Schedule

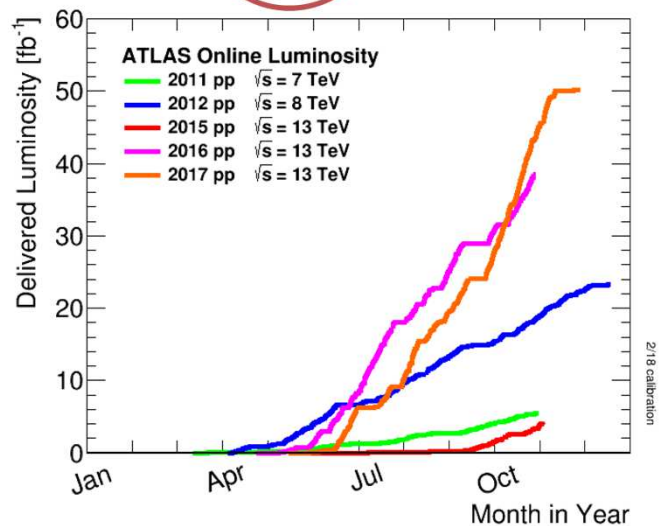
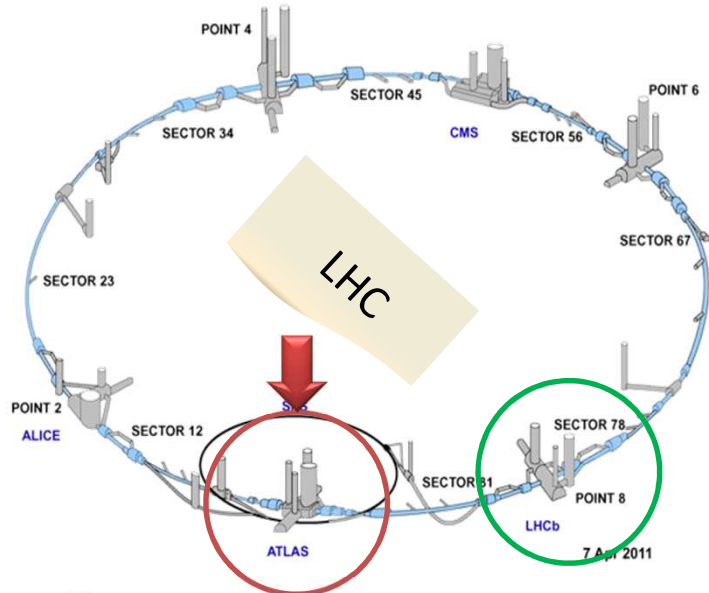
- Timeline and resources

Conclusions

- Conclusions and Outlook

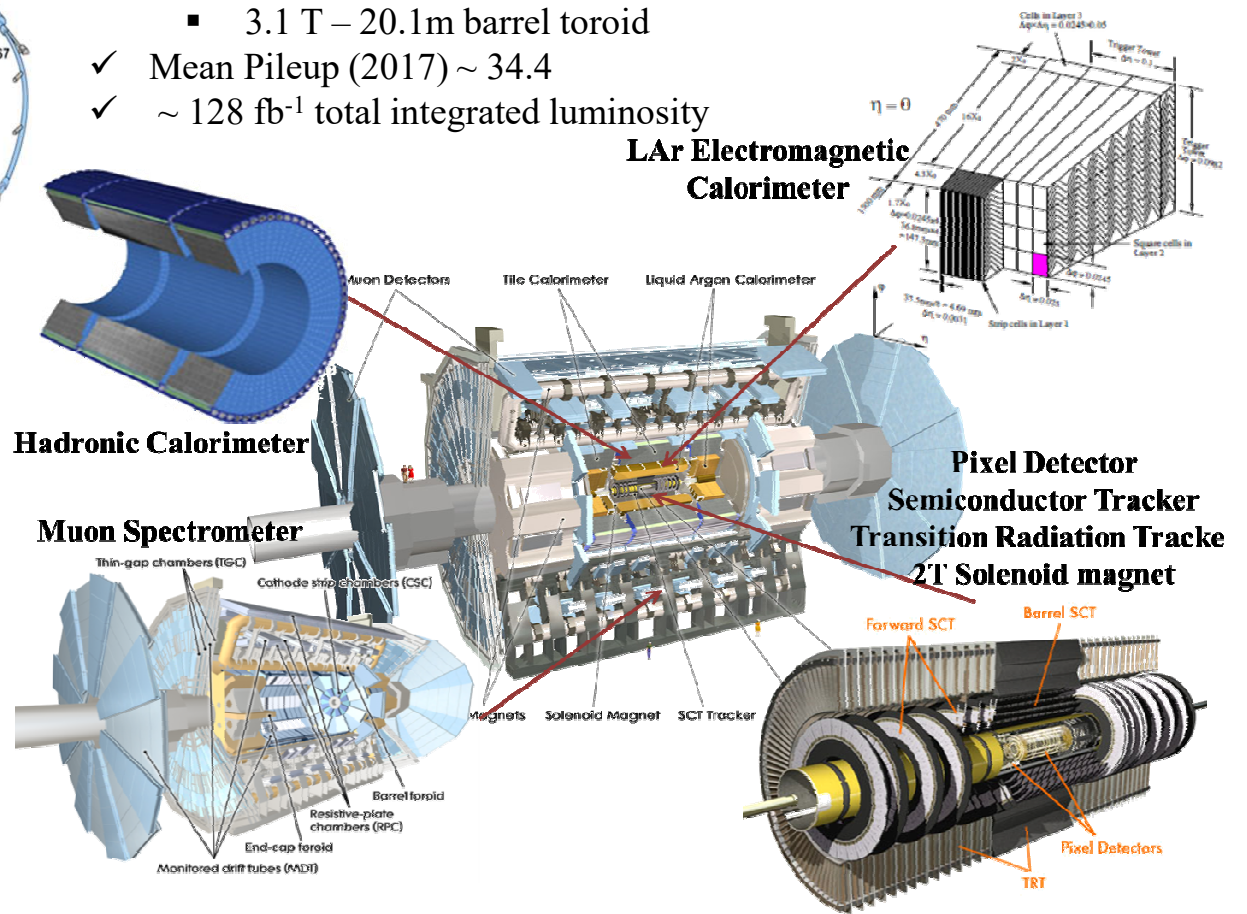
• Introduction

ATLAS and LHC



A Toroidal LHC Apparatus

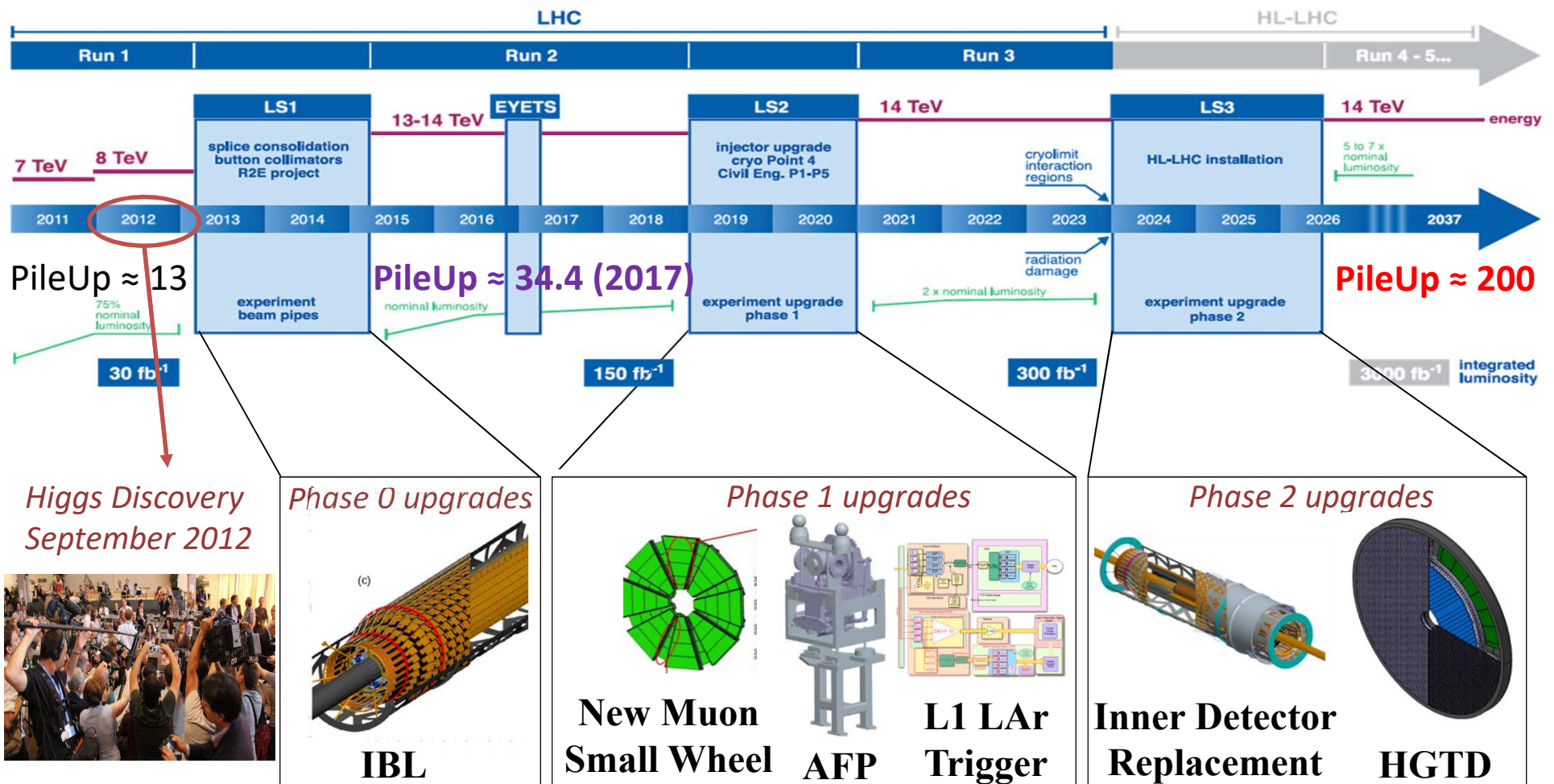
- ✓ Biggest LHC experiment with several sub-detectors
- ✓ 46 x 22 m cylinder, weight of 2000 t, Point 1 of LHC
- ✓ Two superconductive magnets:
 - 2.6 T – 5.3 m long Central solenoid
 - 3.1 T – 20.1m barrel toroid
- ✓ Mean Pileup (2017) ~ 34.4
- ✓ ~ 128 fb⁻¹ total integrated luminosity



• ATLAS Phase II Upgrade

Timeline

LHC / HL-LHC Plan



•HL-LHC Conditions

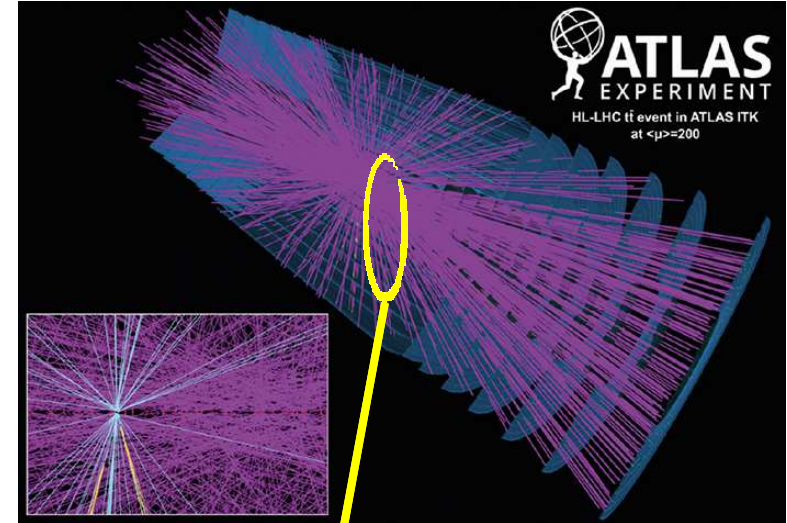
Pileup density

Luminosity

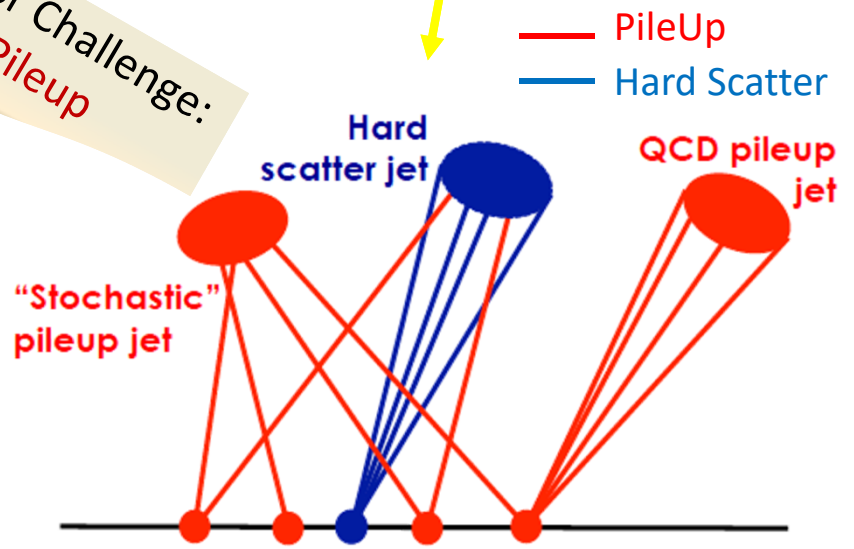
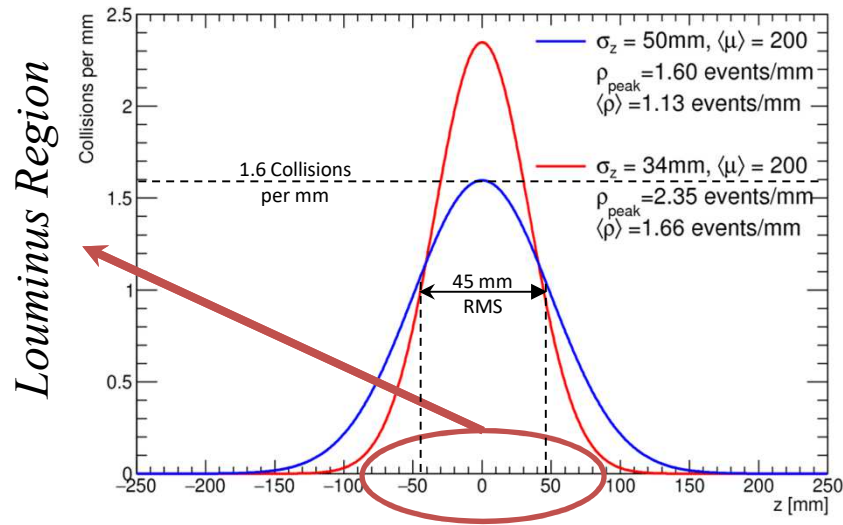
- ✓ Phase I: $< 2.2 \times 10^{34} \text{ cm}^{-2}\text{s}^{-1}$ (300 fb⁻¹)
- ✓ Phase-II : $7.5 \times 10^{34} \text{ cm}^{-2}\text{s}^{-1}$ (4000 fb⁻¹)

Conditions

- ✓ 14 TeV center of mass energy beam - 6000 primary tracks per event
- ✓ No. of collisions per crossing from 34 to 200 within 150 ps at 50 mm space
- ✓ Extended tracking up to $|\eta| < 4.0$



Major Challenge:
Pileup



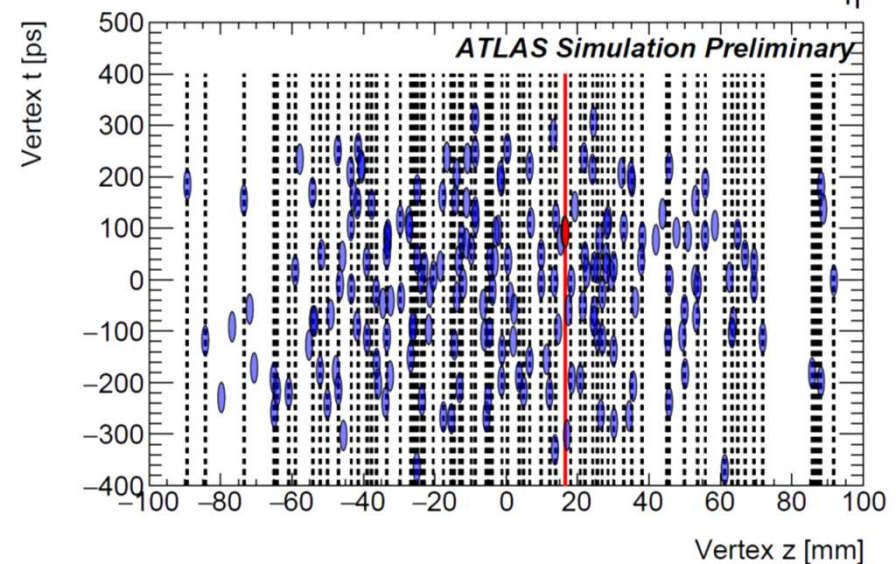
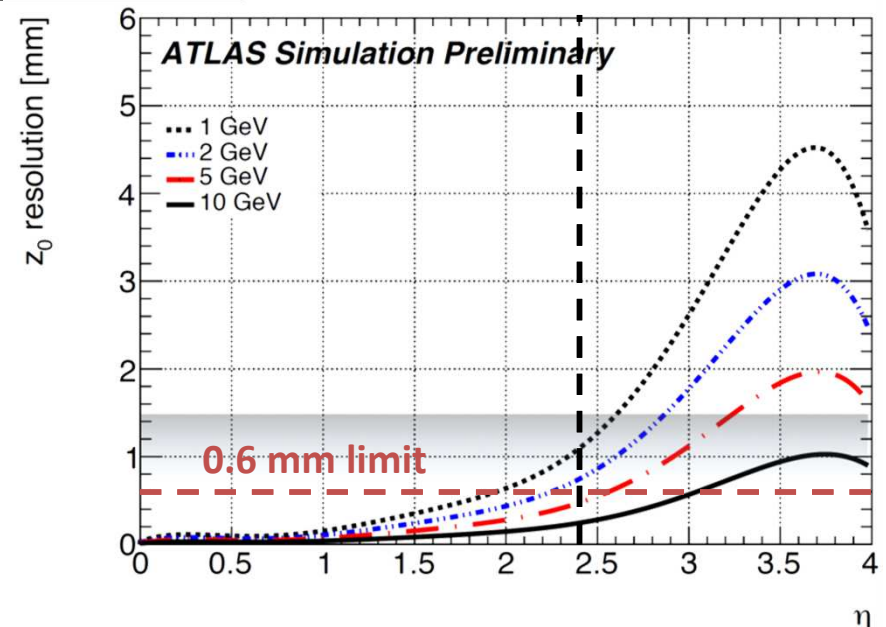
•HL-LHC Conditions

Vertex Resolution

- ✓ Need z_0 resolution < 0.6 mm
- ✓ Tracker much better for central region but reaches the limit $\sim |\eta| = 3$

Time distribution

- ✓ HS present a time peaked distribution with respect to PileUp that are flatter
- ✓ Exploit time spread within pp collisions for vertex separation
- ✓ 30 ps/track transfers $\mu=200$ to $\mu=30$ conditions



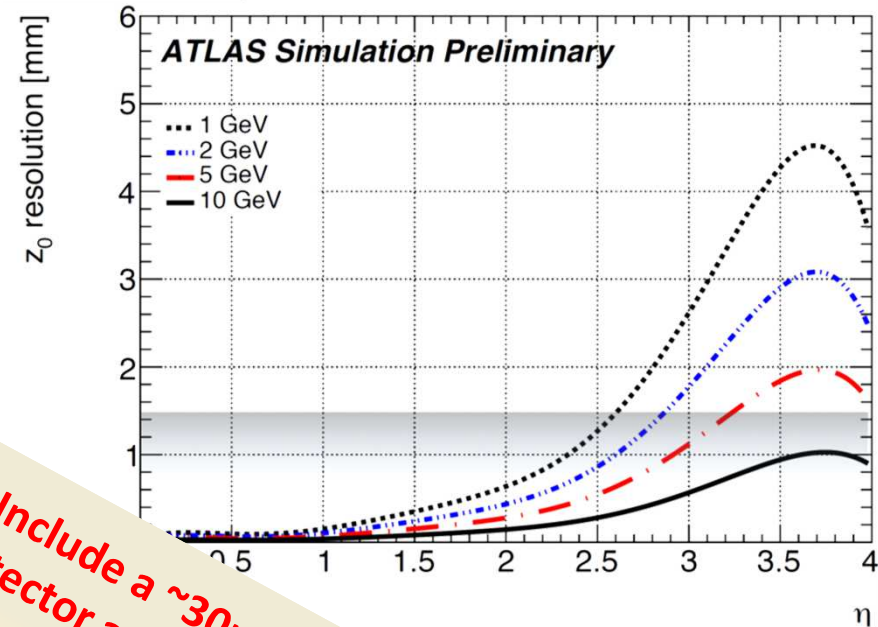
•HL-LHC Conditions

Vertex Resolution

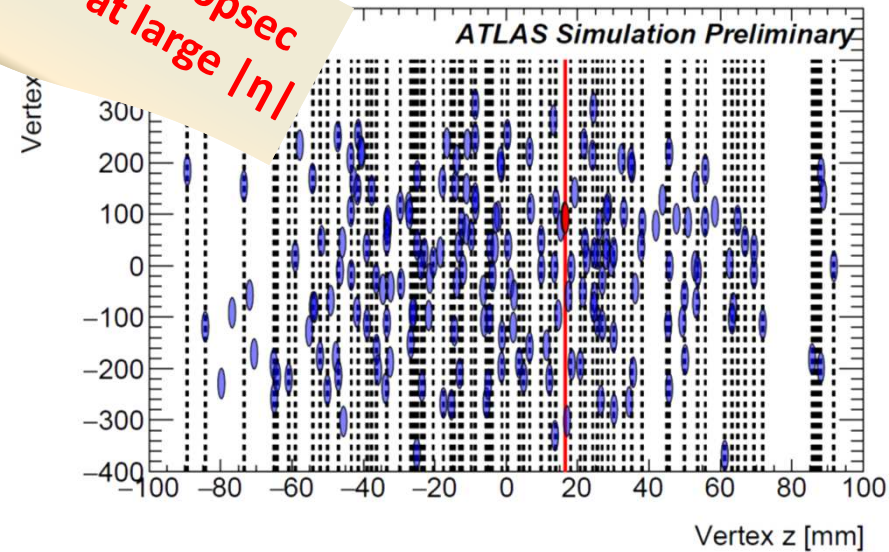
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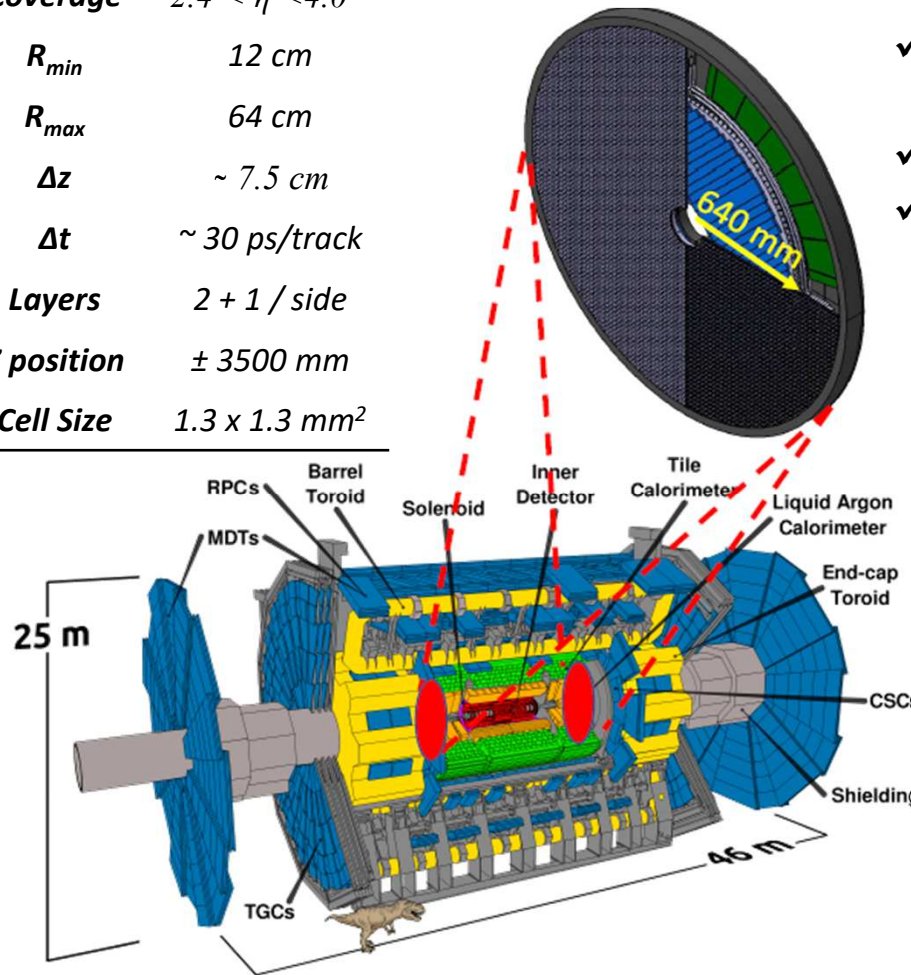
Include a ~30psec detector at large $|\eta|$



•HGTD System

Position and geometry

Specifications for 2023	
Coverage	$2.4 < \eta < 4.0$
R_{min}	12 cm
R_{max}	64 cm
Δz	~ 7.5 cm
Δt	~ 30 ps/track
Layers	2 + 1 / side
Z position	± 3500 mm
Cell Size	1.3×1.3 mm ²

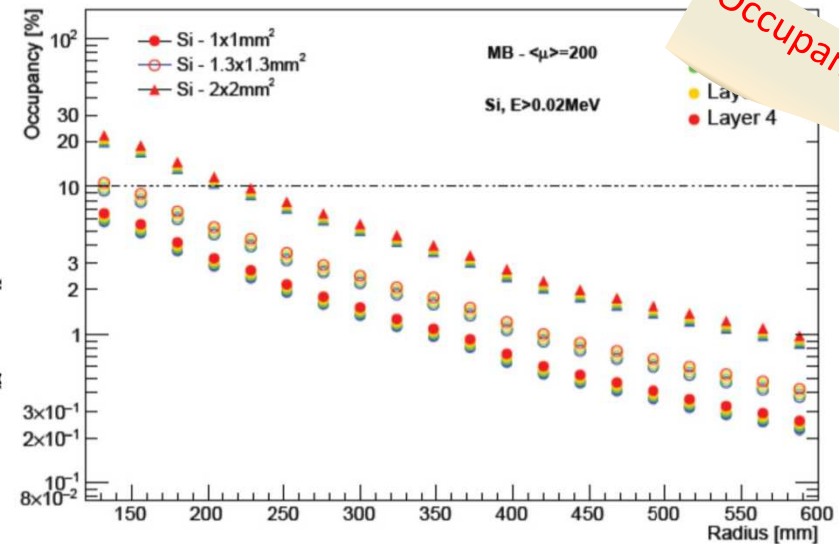


High Granularity Timing Detector

- ✓ Excellent Time resolution (< 30 ps per track)
- ✓ Radiation Hardness (up to 4.5×10^{15} n_{eq}/cm² including mid cycle replacement and safe SF)
- ✓ Low volume modular design (7.5 cm total thickness)
- ✓ Low cost optimised layout
- ✓ Occupancy $< 10\%$ pad with increased granularity



Technology of Choice: Silicon LGAD



• Sensors

Timing Concepts

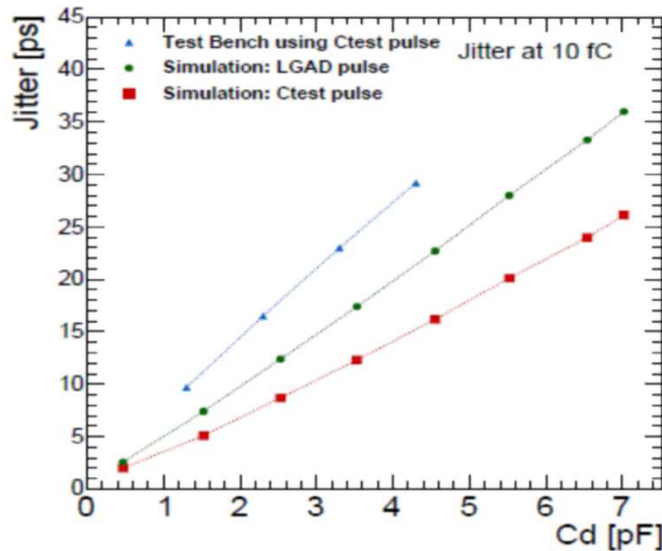
$$\sigma_{elec}^2 = \underbrace{\left(\frac{t_{rise}}{S/N}\right)^2}_{\text{Jitter}} + \underbrace{\left(\frac{V_{thr}}{S/t_{rise}}\right)_{RMS}^2}_{\text{Time walk}} + \underbrace{\left(\frac{TDC_{bin}}{\sqrt{12}}\right)^2}_{\text{Conversion time}}$$

Where: S signal
 N noise
 V_{th} CFD threshold
 t_{rise} rise time

$$\left[\frac{V_{th}}{S/t_{rise}}\right]_{RMS} \propto \left[\frac{N}{dV/dt}\right]_{RMS}$$

$$\frac{t_{rise}}{S/N} \approx \frac{N}{dV/dt}$$

Dependence on Capacitance

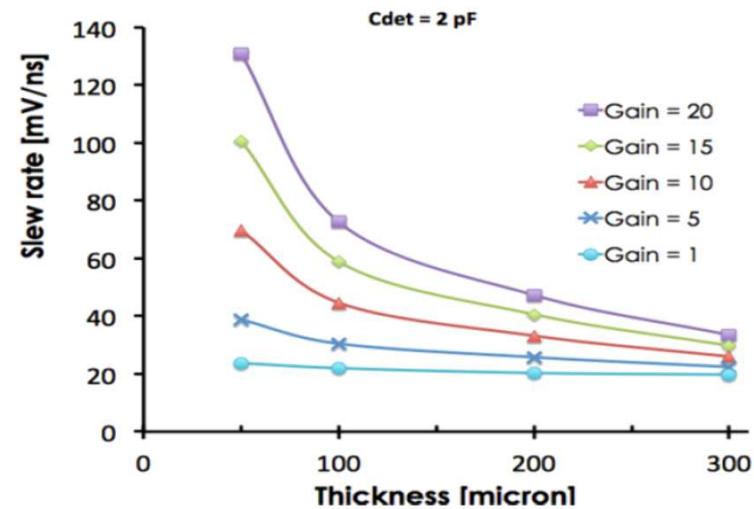


Time Resolution

$$\sigma_{tot}^2 = \sigma_{elec}^2 + \sigma_{Landau}^2 + \sigma_{Clock}^2$$

Fast time resolution:

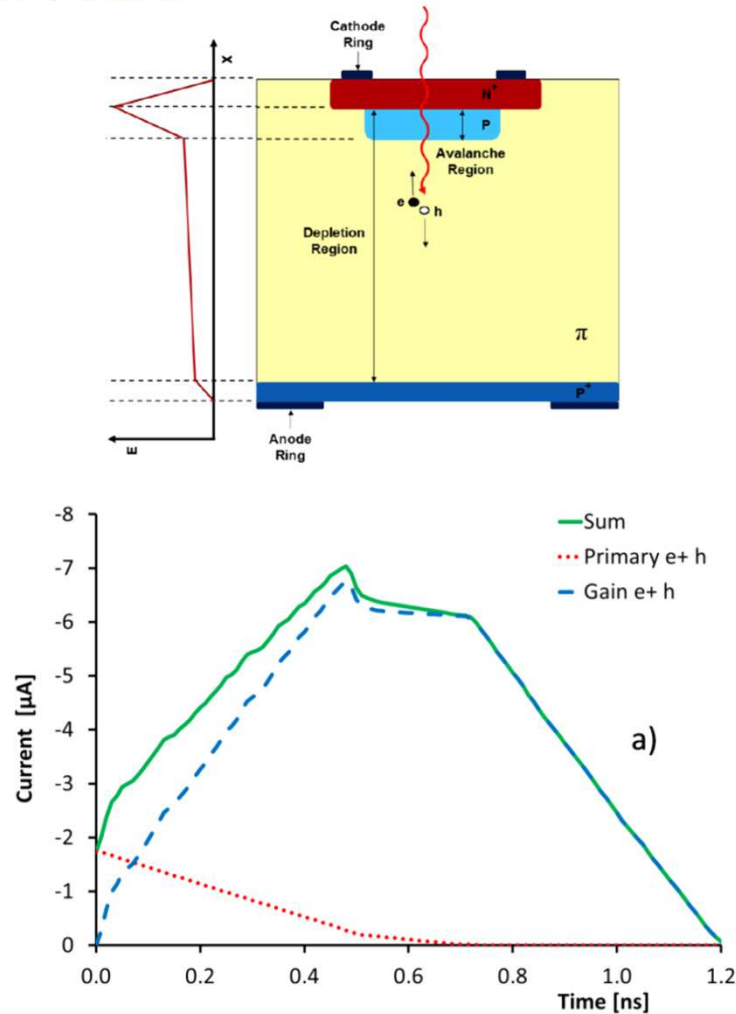
- ✓ Maximize slope (large fast signals)
- ✓ Correct time walk with Constant fraction discriminator
- ✓ Minimize noise to minimize jitter
- ✓ Estimated clock jitter ~ 5 ps
- ✓ Thin silicon sensors with internal gain



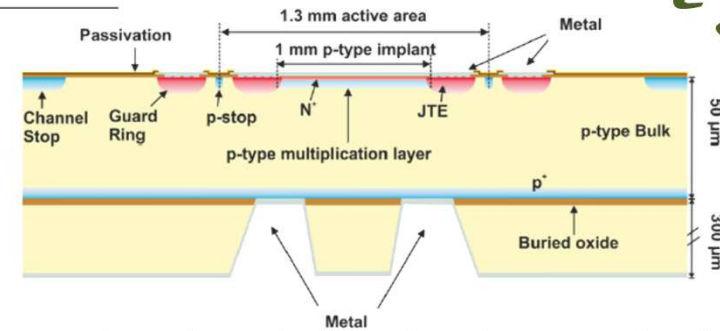
H.-W. Sadrozinski, A. Seiden and N. Cartiglia, 2817 4-Dimensional Tracking with Ultra-Fast Silicon Detectors, arXiv: 1704.08666.

• Sensors

LGADs



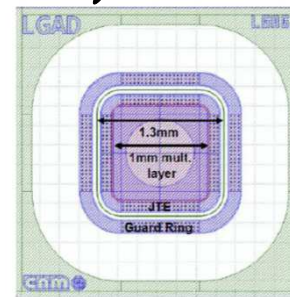
F. Cenna et al., Weightfield2: A fast simulator for silicon and diamond solid state detector, 2822 Nucl. Instrum. Meth. A796 (2015) 149.



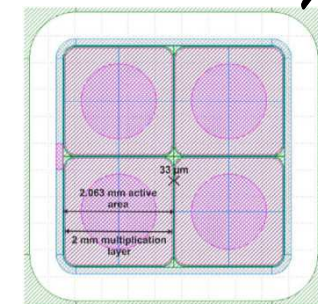
CNM Sa9

- ✓ Developed and initial R&D productions at CNM (Barcelona)
- ✓ Secondary p implant introducing moderate gain HPK, CNM, FBK produced sensors
- ✓ 50 µm thickness on 250 µm support wafer
- ✓ Different implantation doses including Gallium and Carbon
- ✓ Various structures including:
 - ✓ Pad diodes of 1.3 x 1.3 mm²
 - ✓ 2 x 2 arrays of 1 x 1 mm² pad

Single Diode



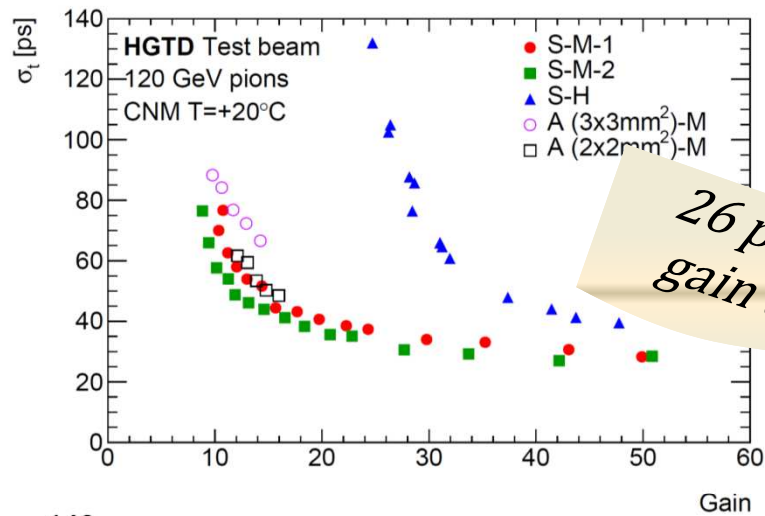
2x2 array



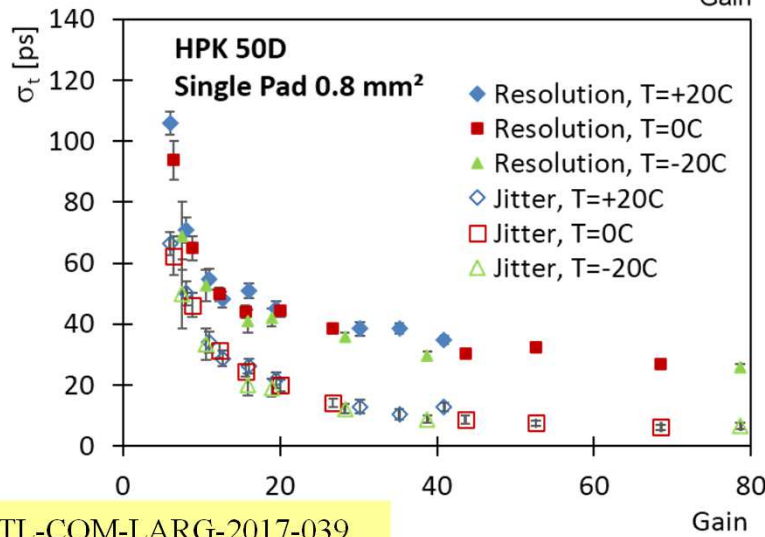
• Sensors

Testbeam Results

Time resolution

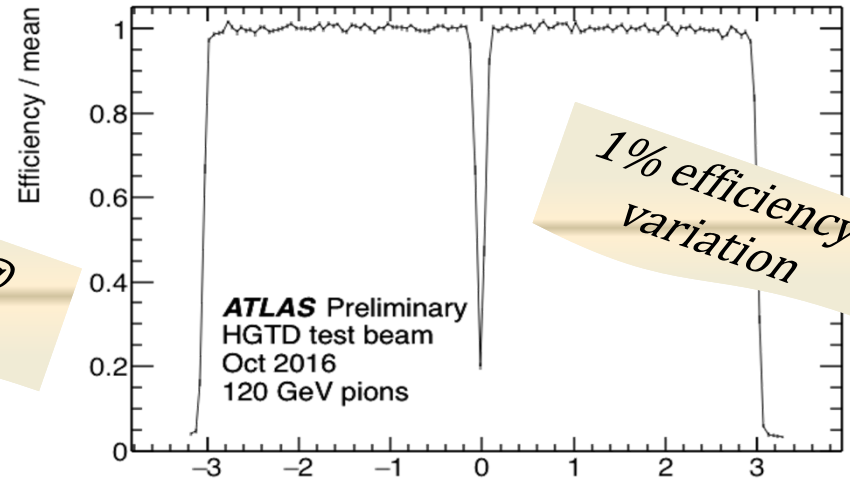


26 psec @
gain of 50

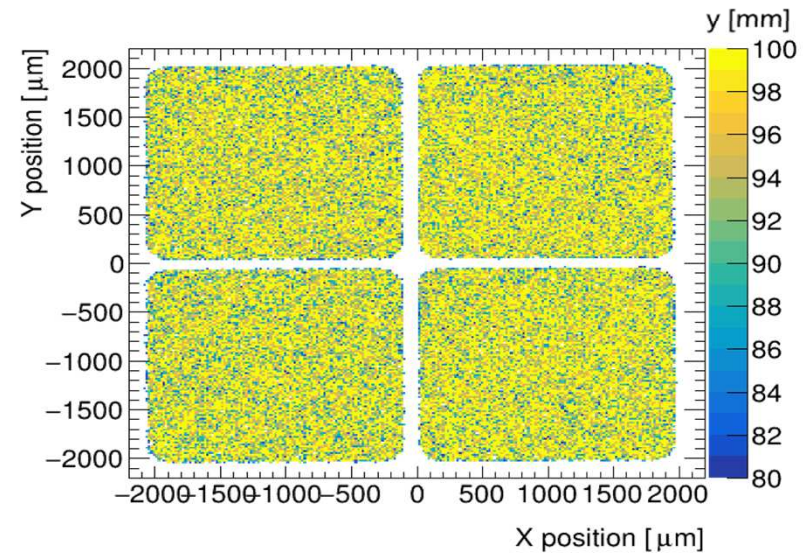


ATL-COM-LARG-2017-039

Efficiency maps

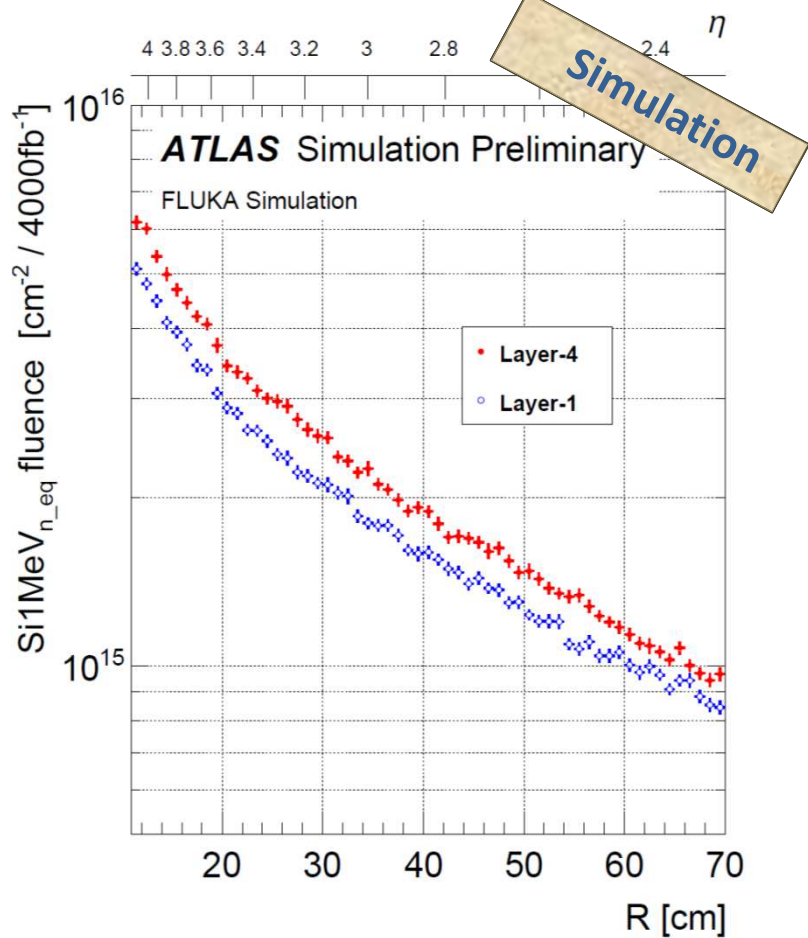


1% efficiency
variation



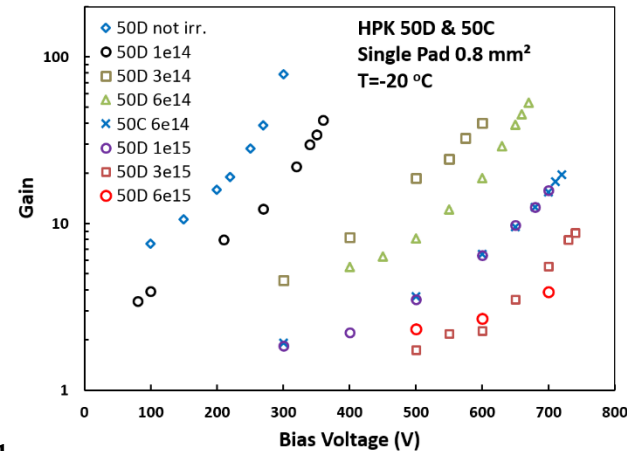
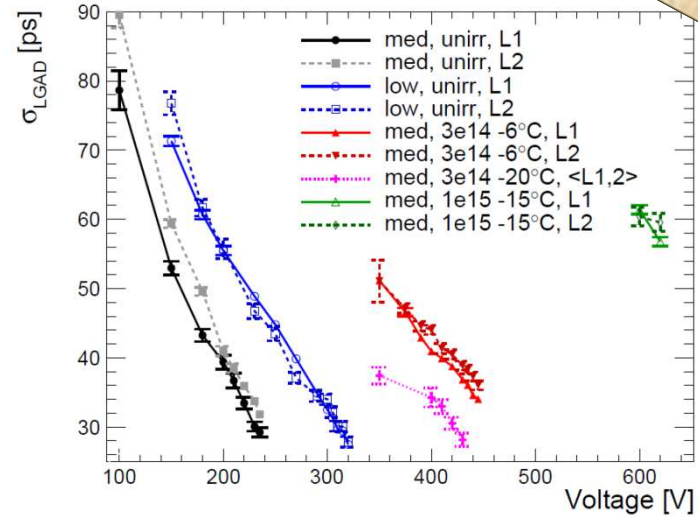
• Sensors

Radiation Hardness



- Similar results Fluka - GCALOR
- Max. ($\eta = 4.0$) after $4000 \text{ fb}^{-1} \sim 4.5 \times 10^{15} \text{ n}_{eq}/\text{cm}^2$ (mid cycle replacement at 2×10^{15})

J. Lange, et al., JINST 12 (2017) P05003

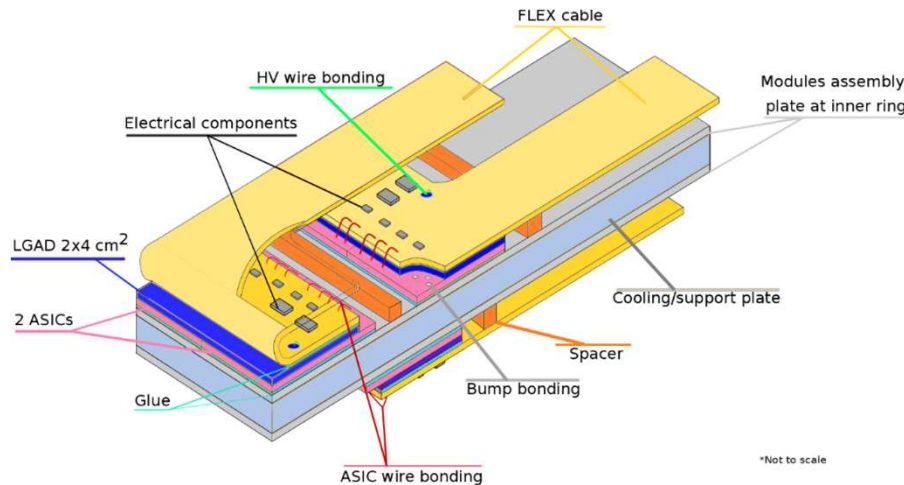


- Thermal neutron irradiation single pad diodes
- Time resolution in the order of 40 ps for gain of 10 - 15

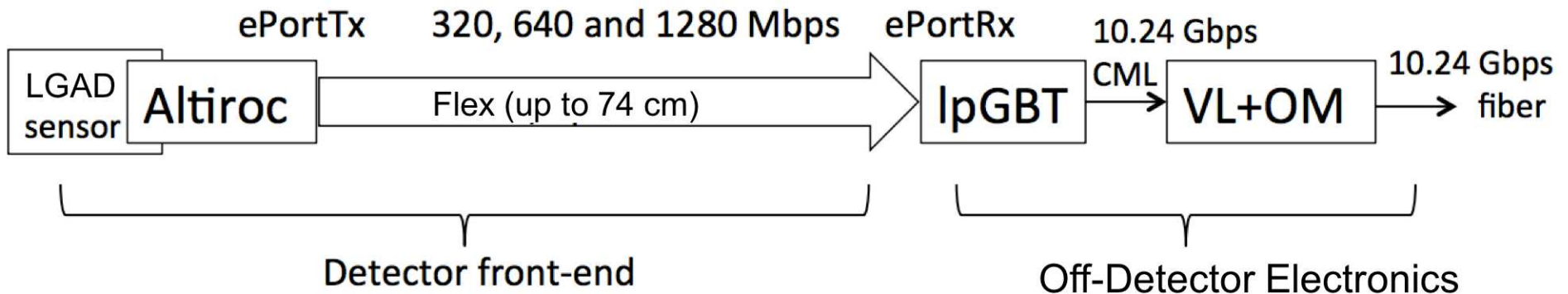
•Integration

ASIC and Signal extraction

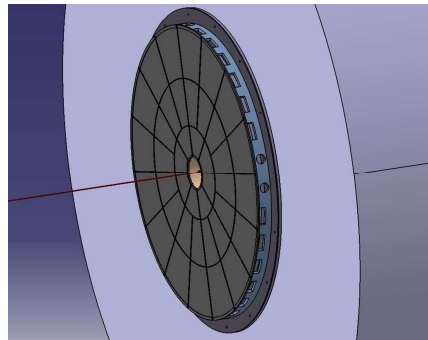
ATLAS LGAD Timing Integrated ReadOut Chip (ALTiRoC)



- 2 x 2 cm die, TSMC 130μm technology
- Bump-bonded to 2 x 4 cm² sensors
- Single pixel readout, 225 channels/ASIC
- Readout Rate:
 - 1 MHz detailed hit info after L1
 - 40 MHz number of hits on outer radii for luminosity estimation
- 25 ps estimated time resolution
- Wire-bonded to capton flex

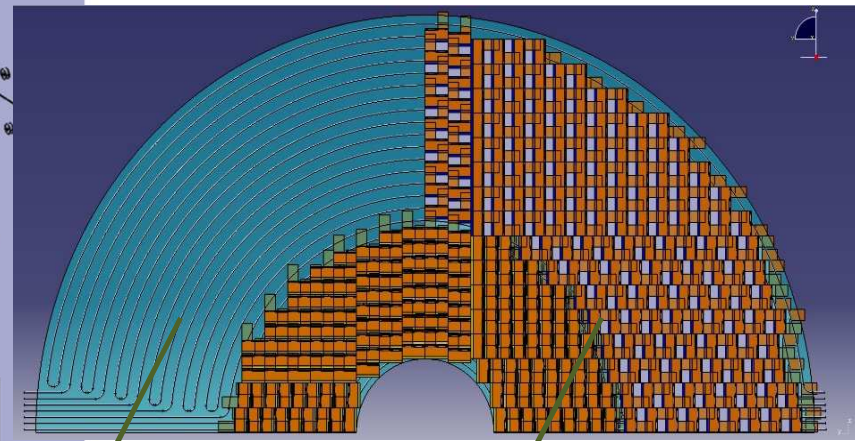
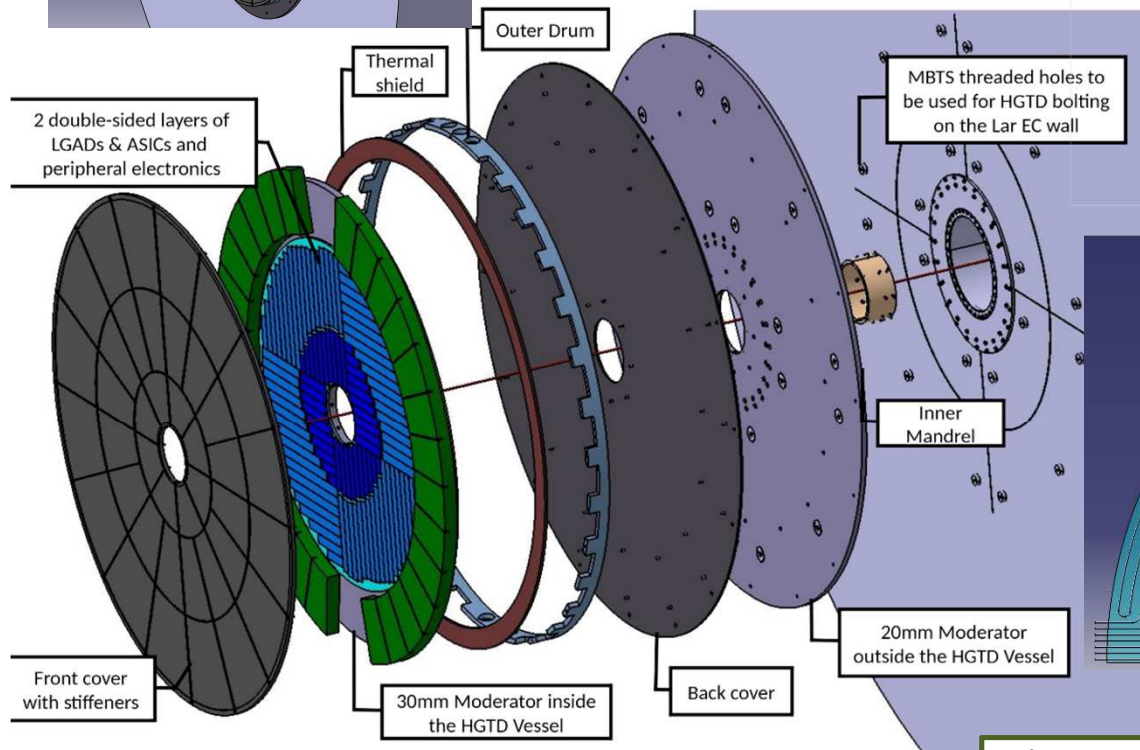
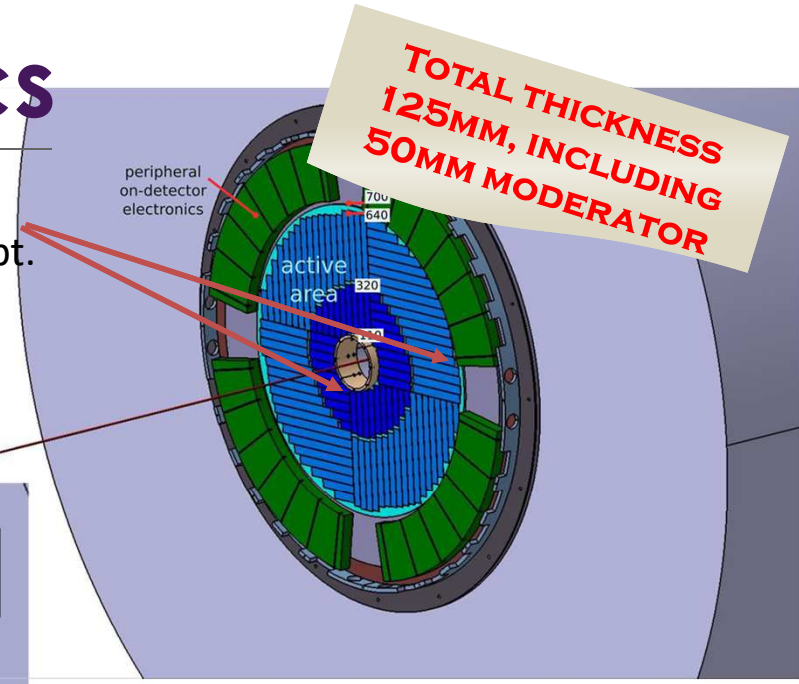


Integration - Mechanics



Forward & backward detector disks with central half rings & stave concept.

- ✓ Total 6 m² LGAD sensors
- ✓ ~ 800 modules in total
- ✓ 2 x 4 cm² per module



Large eta modules, bonded to single half panel

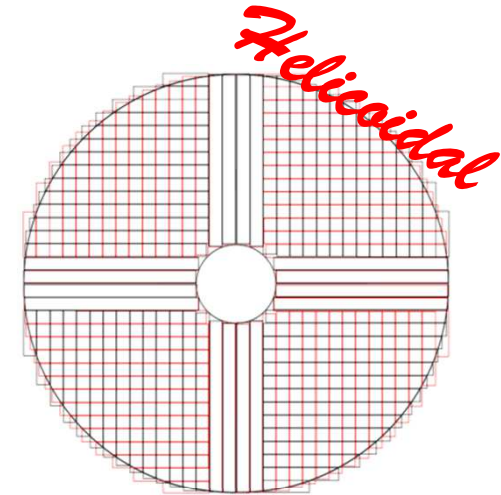
Outer modules where physical staves are considered

• Integration

Layout Optimization

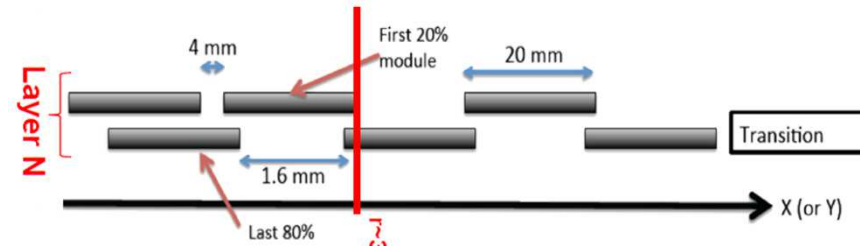
Stave layout

Efficiency		Geometry	
Events with 0 hits	0.7 %	Longest Stave	546 mm
Fraction of events at x or y = 0	52 %	Coverage	91.8 %
		18 staves per quadrant	



Sensor Overlap

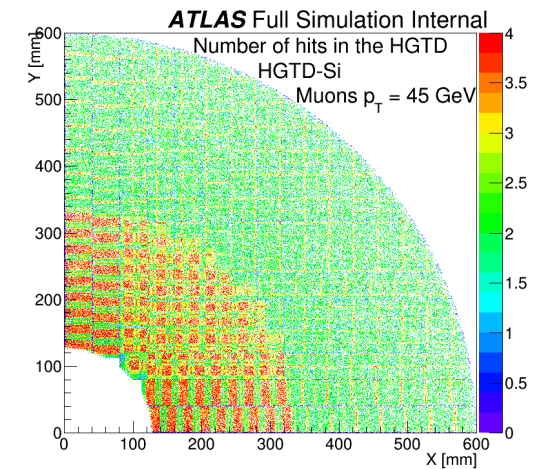
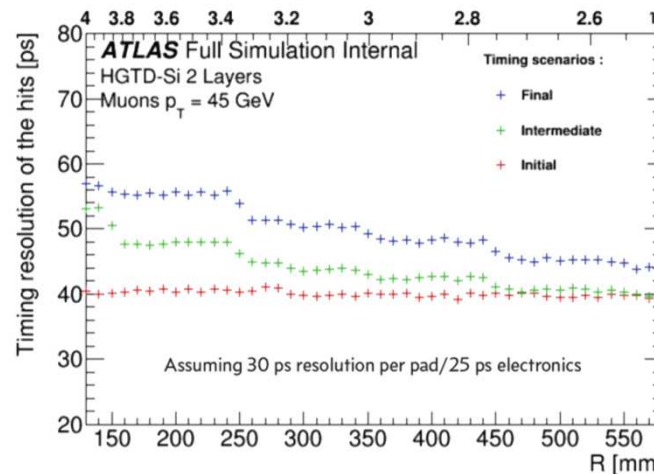
- Resolution degrades with irradiation
- Inner region more affected
- Increase number of hits to recover



Fill Factor

Inter-pad Region

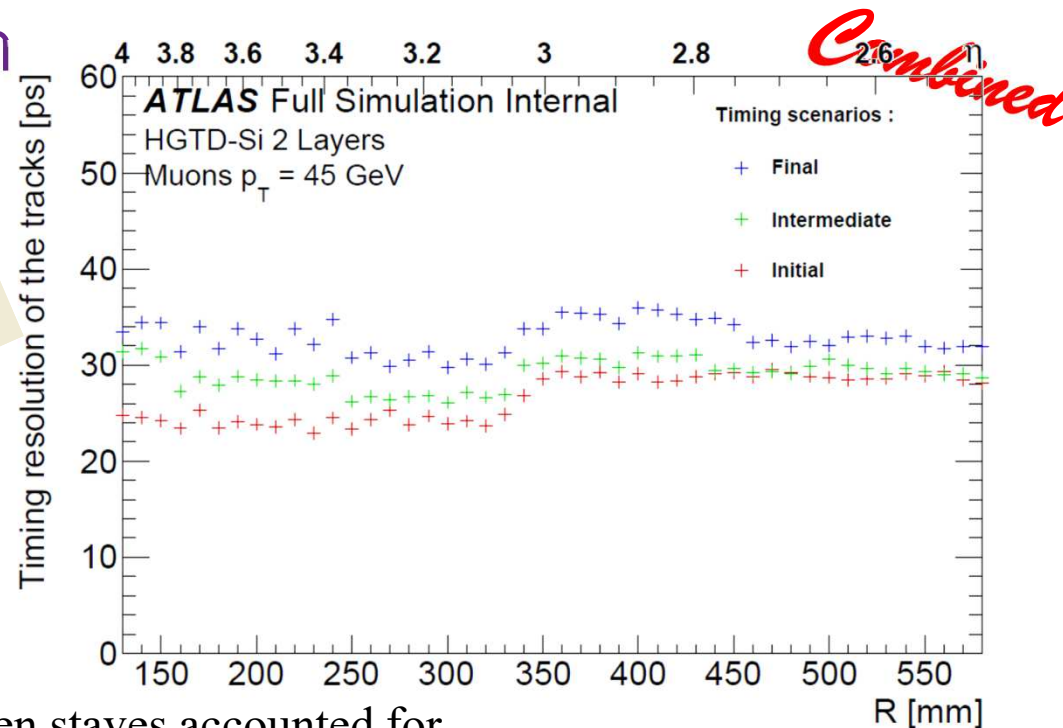
- 30 μm \rightarrow 94 %
- 50 μm \rightarrow 90 %
- 100 μm \rightarrow 82 %



•Physics and Performance

Track resolution

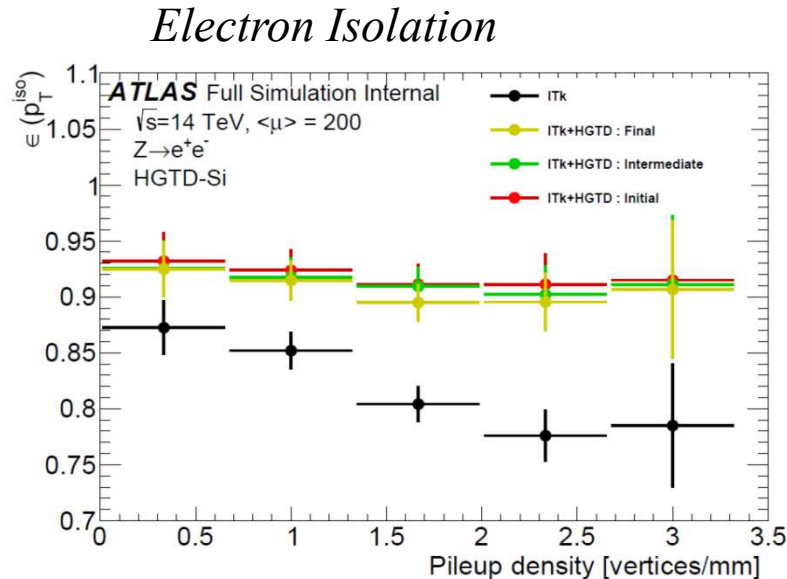
✓ ~2 hits at large radius
($R > 320$ mm), overlap 20 %
✓ ~3 hits at low radius
($R < 320$ mm), overlap 80 %



- ✓ Dead regions between staves accounted for
 - 4 mm for 80 % overlap
 - 16 mm for 20 % overlap
- ✓ Track resolution always < 40 psec
- ✓ 3 different timing scenarii
 - *Initial* : 30 psec per pad and 25 psec for electronic
 - *Intermediate* : timing resolution after 2000 fb^{-1} (with inner layer replacement)
 - *Final* : timing resolution after 4000 fb^{-1}

•Physics and Performance

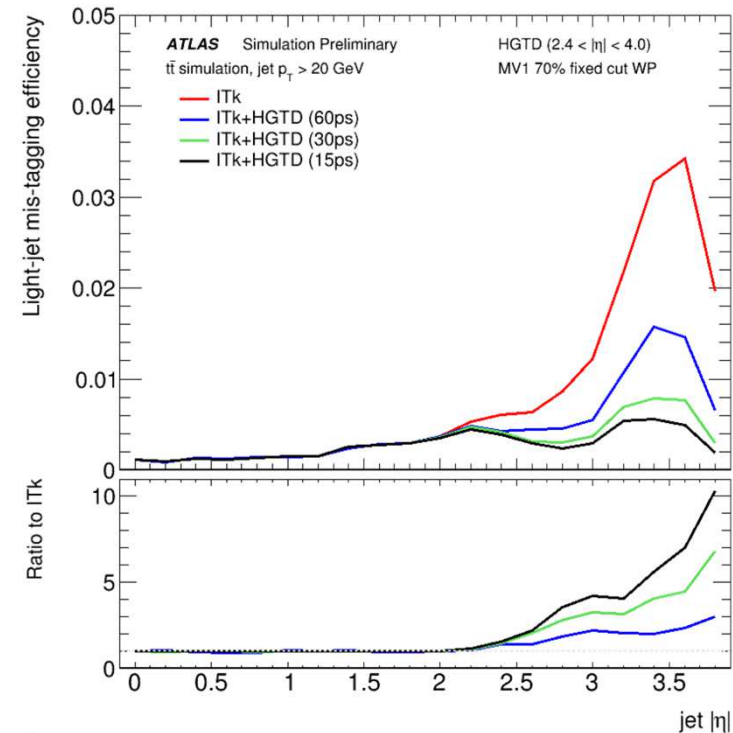
Performance



- ✓ 2 layers/side with overlap
- ✓ Average efficiency ~93% at all cases
- ✓ ITk only average efficiency ~83%

Performance plots currently been updated for new geometry

B-tagging performance



- ✓ 100% Efficient does not use η parametrization nor fill factor
- ✓ Initial assumes 30psec across the whole detector
- ✓ Slight degradation between initial and final, though larger loss from hit efficiency

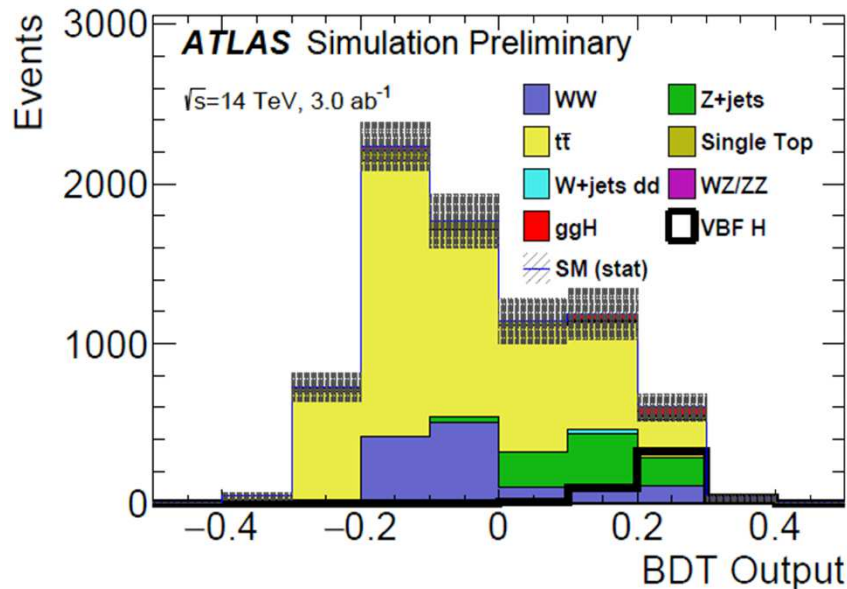
•Physics and Performance

Some EW channels

$$qqH \rightarrow qqWW^* \rightarrow qq + e\nu_e \mu\nu_\mu$$

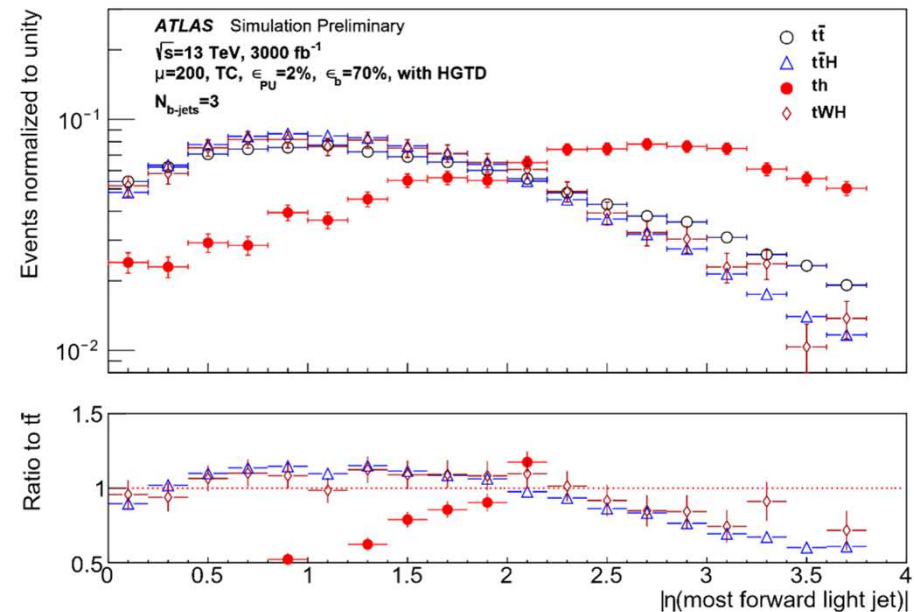
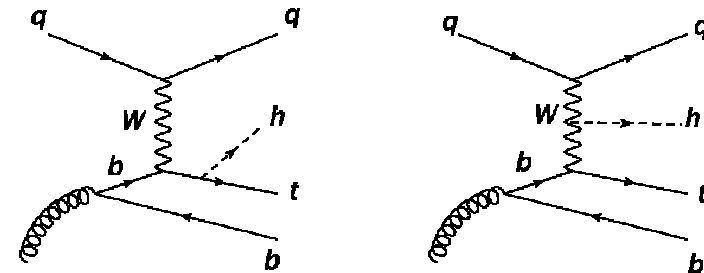
- **8% relative improvement**
 - 43% background rejection
 - 3% PU efficiency
 - BDT analysis
 - *Top dominated background due to forward b-tagging*

VBF processes under investigation



$tH(\rightarrow bb)$

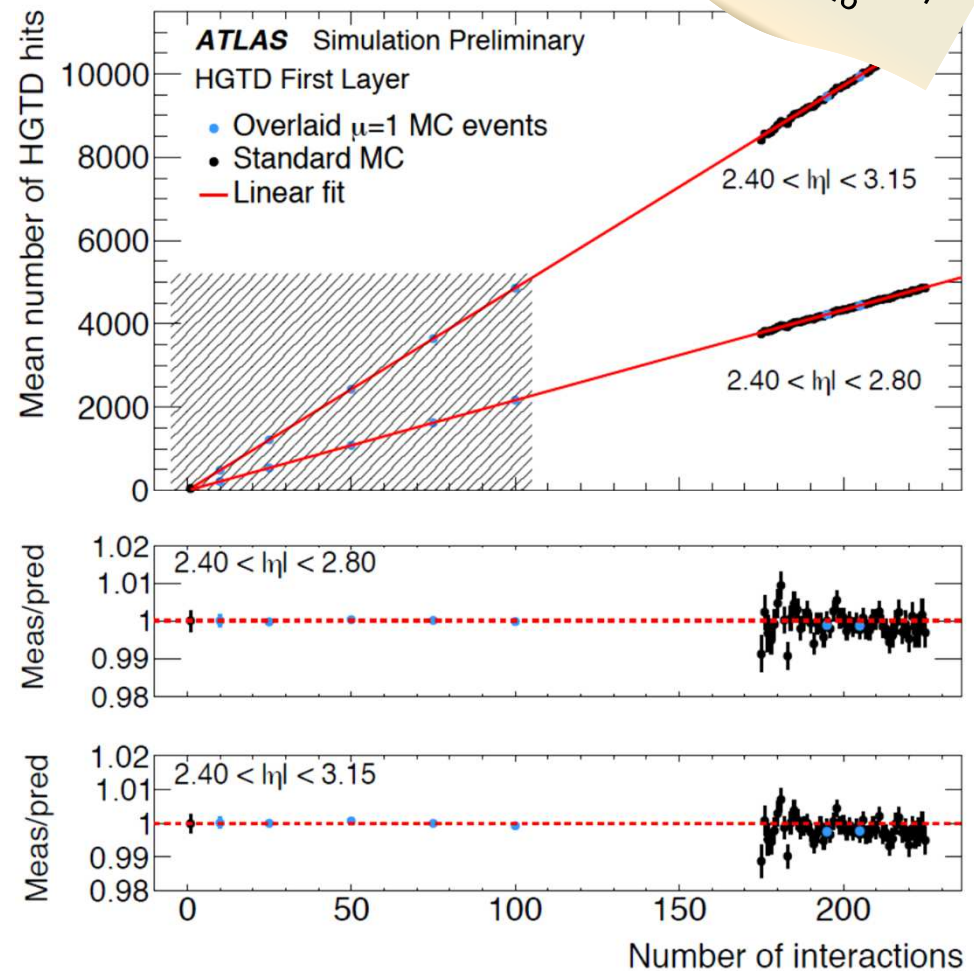
- **11% relative improvement**



•HGTD as Luminometer

On line and off-line estimation

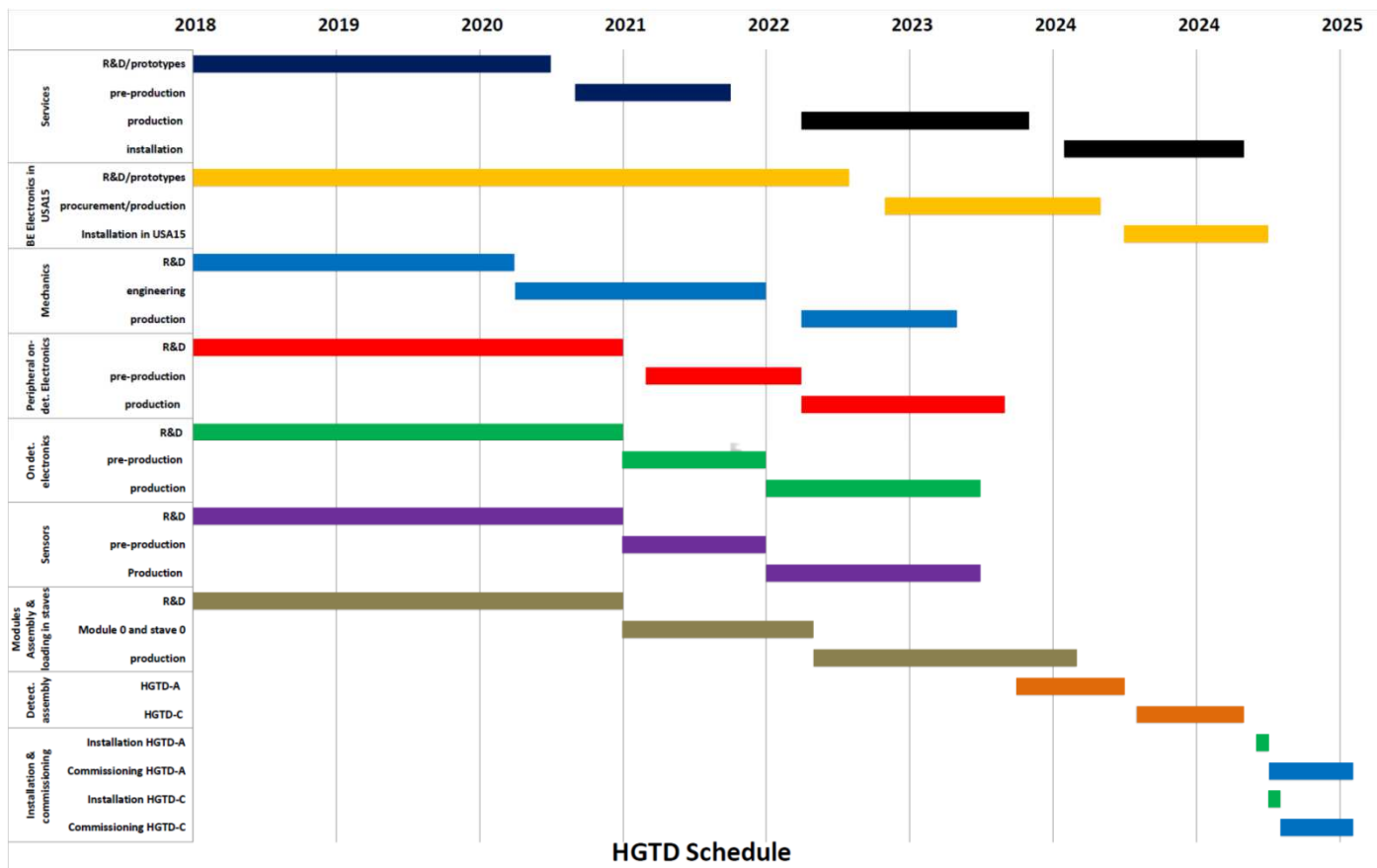
- **linear dependence of number of hits on number of interactions**
 - Count hits in the region of $320 \text{ mm} < R < 640 \text{ mm}$
 - 0.1% expected statistical uncertainty for 1 sec integration time
 - Low systematics
 - Out of time sideband subtraction
 - Hit count per ASIC and BCID
- **On-line Estimation**
 - 40MHz readout for real time estimation
 - Provide per BCID interactive estimate
 - Total latency of 440 ns (100 ASIC+ 340 ns fiber)



•Schedule

Important mile-stones

- 2018 - 2020: Sensor, ASIC, electronics and services RnD
- 2021 - 2024: Fabrication and module assembly
- 2025 - 2026: Installation and Commissioning



•Conclusions and Outlook

Sensors, ASIC, Integration and Radiation Hardness

So far....

Physics

- ✓ Very promising results for pileup rejection in the high η region where VBF and exotics will benefit
- ✓ High jet single purity for invisible searches

Sensors

- ✓ 26 ps time resolution for single un-irradiated 1.3mm² diodes
- ✓ 99% uniformity with low inefficiencies in the inter-pad regions
- ✓ Operations up to 6×10^{15} n_{eq}/cm², meeting the radiation hardness requirements
- ✓ Any timing degradation due to early breakdown

Integration

- ✓ First ASIC prototypes successfully assembled at IFAE and tested in HGTD September CERN testbeam
- ✓ Validate full ASIC design and expect first prototype at the last quarter of 2018